

SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

ABSTRACT

A semiconductor device includes a common wire that sequentially connects three or more pads; bonding portions at which a side surface of the wire is bonded to the pads; and looping portions looped from the bonding portions onto the other pads adjacent to the pads, the bonding portions and the looping portions are formed alternately. When the pads are recessed from the surface of semiconductor chips, the common wire is crushed to a thickness greater than the recess depth of the pads to be made into a flat shape. Thus, on the semiconductor device, wire connection is performed with a smaller bonding count while reducing damage to the semiconductor chips, and at the same time bonding is performed efficiently to the electrodes recessed from the surface of the semiconductor chips.

FIGURE 1